CLAIMS

What is claimed is:

1	1. A device enclosure comprising:
2	a thermo-siphon device embedded in an enclosure skin.
1 2	2. The device of claim 1, wherein the device is an electronic device.
1 2	3. The device of claim 2, wherein the device enclosure is a computer chassis.
1 2	4. The device of claim 1, wherein the device is a non-electronic device.
1 2	5. The device of claim 1, wherein the thermo-siphon device is a heat pipe.
1 2	6. The device of claim 1, wherein the thermo-siphon device is a strip of a high efficiency conduit material.
1 2	7. The device of claim 1, wherein the thermo-siphon device is an integral part of the skin.
1 2	8. The device of claim 7, wherein the thermo-siphon device is embedded in the skin during the manufacturing process of the skin.
1 2	9. The device of claim 1, wherein the skin is fabricated from a metallic material.

1	10. The device of claim 1, wherein the thermo-siphon device is		
2	embedded in a skin cavity.		
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1	11. The device of claim 10, wherein the cavity is created during		
2	a fabrication process of the skin.		
1	12. The device of claim 1, wherein the skin partially encloses		
2	the thermo-siphon device.		
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1	13. The device of claim 12, wherein a portion of the thermo-		
2	siphon device is exposed to an interior of the enclosure.		
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1	14. The device of claim 12, wherein a portion of the thermo-		
2	siphon device is exposed to a heat sink.		
1	15. The device of claim 1, wherein the thermo-siphon device is		
2	not an integral part of the skin.		
1	16. The device of claim 15, wherein the thermo-siphon device		
2	can be inserted and removed from a skin cavity by accessing the interior		
3	of the enclosure.		
1	17. The device of claim 1, wherein the thermo-siphon device is		
2	secured to a skin cavity through the means selected from the group		
3	consisting of a support provided by skin cavity walls, a thermal epoxy,		
4	and an interference fit with the skin cavity.		
1	The device of claim 1 rub again a mostallia plata intenference		
1	18. The device of claim 1, wherein a metallic plate interfaces a		
2	heat source with the thermo-siphon device.		

19.	A system comprising:
	a housing including a thermo-siphon device embedded in
housing skir	n.
20.	The system of claim 19, wherein the thermo-siphon device
is a heat pip	e.
21.	The system of claim 19, wherein the thermo-siphon device
is a strip of l	high efficiency conduit material.
22.	The system of claim 19, wherein the housing is a computer
chassis.	
23.	The system of claim 19, wherein the thermo-siphon device
is an integra	l part of the housing skin.
24.	A computer chassis comprising:
	a thermo-siphon device embedded in a computer chassis
skin.	
25.	The computer chassis of claim 24, wherein the thermo-
siphon devi	ce is a heat pipe.
26.	The computer chassis of claim 24, wherein the computer
chassis is a r	notebook computer base.
27.	The computer chassis of claim 24, wherein the thermo-
	housing skin 20. is a heat pip 21. is a strip of 1 22. chassis. 23. is an integral 24. skin. 25. siphon devi-

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siphon device is an integral part of the skin.

L	28. The computer chassis of claim 27, wherein the thermo-
2	siphon device is embedded in the skin during the manufacturing process
3	of the skin.